

AM7338N-T1-PF-VB Datasheet N-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}$ (Ω) Typ.	I _D (A)	Q _g (Typ.)		
30	0.004 at $V_{GS} = 4.5 \text{ V}$	60	33.5 nC		
30	0.005 at V _{GS} = 2.5 V	50	33.3 110		

FEATURES

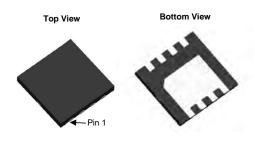
Halogen-free According to IEC 61249-2-21 Definition



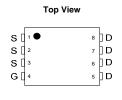
- Trench Power MOSFET
- 100 % $\rm R_{\rm g}$ and UIS Tested Compliant to RoHS Directive 2002/95/EC

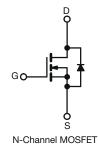
APPLICATIONS

- Motor Control
- Industrial
- Load Switch
- ORing



DFN 3x3 EP





ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted) Parameter Symbol Limit Unit Drain-Source Voltage V_{DS} 30 ٧ Gate-Source Voltage V_{GS} ± 20 T_C = 25 °C 60^{a, e} 40^{a, e} T_C = 70 °C Continuous Drain Current (T_J = 150 °C) I_D T_A = 25 °C 22^{b, c} 15^{b, c} $T_{\Delta} = 70 \, ^{\circ}C$ Pulsed Drain Current (t = 300 μs) I_{DM} 150 T_C = 25 °C 35 Continuous Source-Drain Diode Current I_S T_A = 25 °C 3.3^{b, c} Single Pulse Avalanche Current I_{AS} 20 L = 0.1 mHSingle Pulse Avalanche Energy EAS m.l 20 T_C = 25 °C 52 T_C = 70 °C 33 P_D W Maximum Power Dissipation T_A = 25 °C 3.7^{b, c} T_A = 70 °C 2.4^{b, c} T_J , T_{stg} Operating Junction and Storage Temperature Range - 55 to 150 °C Soldering Recommendations (Peak Temperature) 260

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	24	33	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	1.9	2.4]	

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- d. Maximum under steady state conditions is 90 °C/W.
- e. Calculated based on maximum junction temperature. Package limitation current is 80 A.



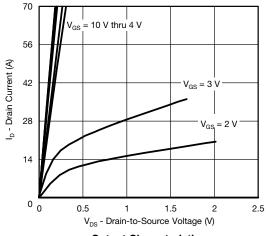
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050A		30		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 5.6			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	0.5		1.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
7. 0 . 1	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1	μА	
Zero Gate Voltage Drain Current		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55 ^{\circ}\text{C}$			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 V$, $V_{GS} = 10 V$	30			Α	
	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		0.0040		Ω	
Drain-Source On-State Resistance ^a		$V_{GS} = 2.5 \text{ V}, I_D = 7 \text{ A}$		0.0050			
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_D = 10 \text{ A}$		65		S	
Dynamic ^b			I.	•			
Input Capacitance	C _{iss}			6000		pF	
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		406			
Reverse Transfer Capacitance	C _{rss}			360			
Total Gate Charge	Q _g V	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$		68	102		
				33.5	51		
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		7.7			
Gate-Drain Charge	Q_{gd}			13.8			
Gate Resistance	R_{g}	f = 1 MHz	0.3	0.7	1.4	Ω	
Turn-On Delay Time	t _{d(on)}			24	45		
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		24	45		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 10 A, V_{GEN} = 4.5 V, R_g = 1 Ω		32	60		
Fall Time	t _f			12	24		
Turn-On Delay Time	t _{d(on)}			14	28	- ns -	
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		13	26		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω		33	60		
Fall Time	t _f			8	16		
Drain-Source Body Diode Characteristi	cs			•			
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C		35			
Pulse Diode Forward Current	I _{SM}			70		A	
Body Diode Voltage	V_{SD}	I _S = 3 A, V _{GS} = 0 V		0.7	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}			21	40	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	L = 10 A dl/dt = 100 A/vo T = 05 °C		10	20	nC	
Reverse Recovery Fall Time	t _a	I _F = 10 A, dl/dt = 100 A/μs, T _J = 25 °C		9		ns	
Reverse Recovery Rise Time	t _b			12			

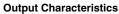
Notes:

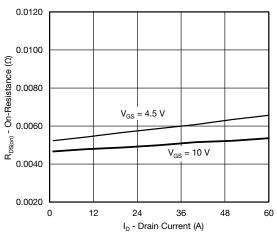
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

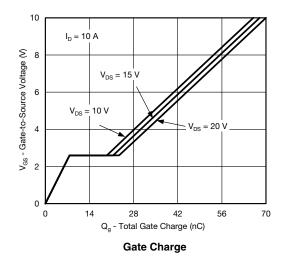


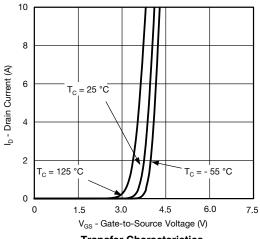




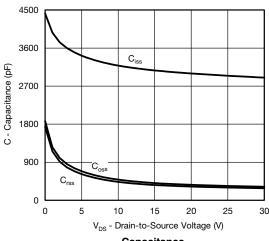


On-Resistance vs. Drain Current and Gate Voltage

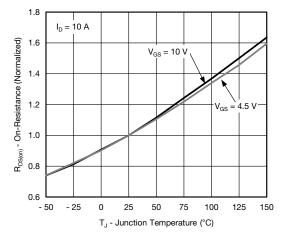




Transfer Characteristics

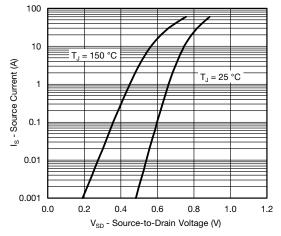


Capacitance

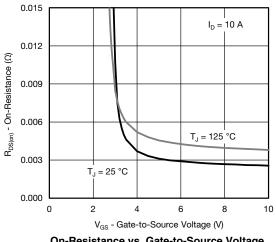


On-Resistance vs. Junction Temperature

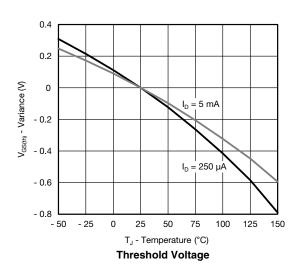


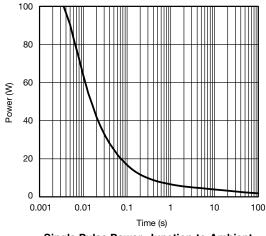


Source-Drain Diode Forward Voltage

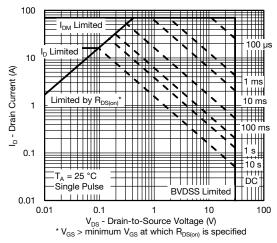


On-Resistance vs. Gate-to-Source Voltage



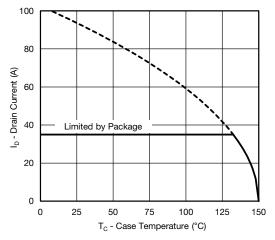


Single Pulse Power, Junction-to-Ambient

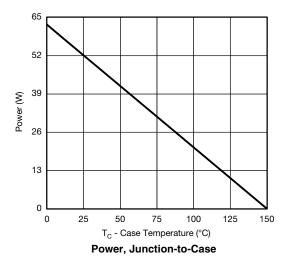


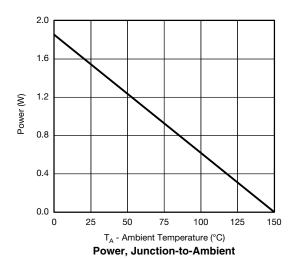
Safe Operating Area, Junction-to-Ambient





Current Derating*

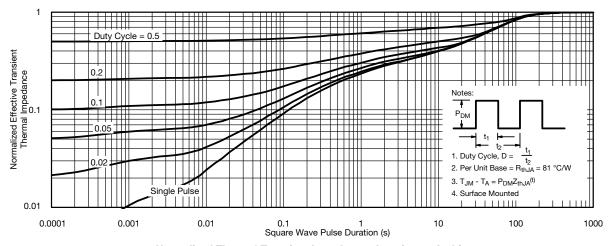




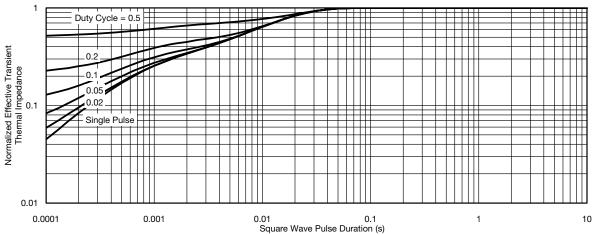
服务热线:400-655-8788 5

^{*} The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



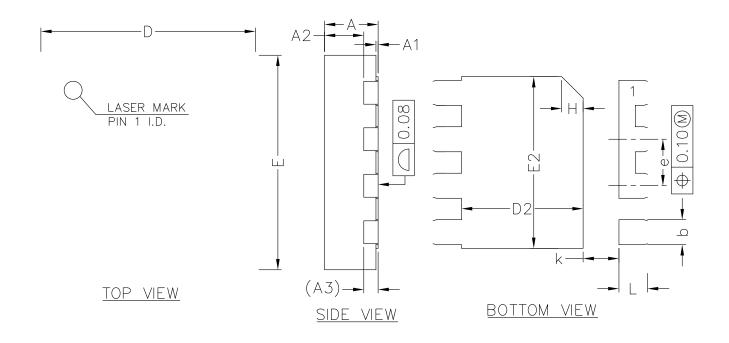


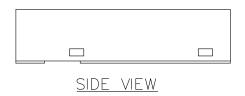
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case







COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
Α	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2	0.50	0.55	0.60
А3	0.20REF		
Ь	0.30	0.35	0.40
D	2.90	3.00	3.10
E	2.90	3.00	3.10
D2	1.60	1.70	1.80
E2	2.30	2.40	2.50
е	0.55	0.65	0.75
K	0.40	0.50	0.60
L	0.35	0.40	0.45



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